

PROCESS CHANGE NOTICE
 PRODUCT CHANGE NOTICE
**MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE
 THAT MAY AFFECT THE FOLLOWING CATEGORIES:**

<input type="checkbox"/> DESIGN	<input type="checkbox"/> WAFER FAB	<input checked="" type="checkbox"/> ASSEMBLY	<input type="checkbox"/> TEST	<input type="checkbox"/> ELEC/MECH SPECS
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AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

CHANGE FROM: Molding Compound at Carsem is Sumitomo G700J

CHANGE TO: Molding Compound Change at Carsem to Sumitomo G600C

JUSTIFICATION: The Sumitomo G700J mold compound was discontinued at Carsem. The Sumitomo G600C is same molding compound currently used at ATP for Maxim for the same SSOP packages.

There are no changes in the form, fit, or function of the devices.

Please see the attached reliability report, R28049CQ.

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.



Deborah Meeker / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative or Deborah Meeker, PCN Coordinator
 408-601-5618 / pcn.coordinator@maximintegrated.com

Bill of Materials Comparison at Carsem (Old and New)

	Carsem (CURRENT)	Carsem (NEW)	Change
Assembly Location	Carsem, Malaysia	Carsem, Malaysia	None
Package Type	SSOP	SSOP	NONE
Leadframe type	Copper	Copper	NONE
Die Attach type (conductive/non-conductive)	Conductive	Conductive	NONE
Die Attach Brand	Ablebond 84-1LMISR4	Ablebond 84-1LMISR4	NONE
Wire Type	Gold	Gold	NONE
Mold Compound	Sumitomo G700J	Sumitomo G600C	YES